

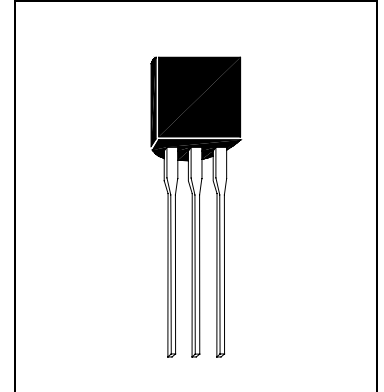


# HSB564A

PNP EPITAXIAL PLANAR TRANSISTOR

## Description

The HSB564A is designed for general purpose low frequency power amplifier applications.



## Absolute Maximum Ratings

- Maximum Temperatures  
Storage Temperature ..... -55 ~ +150 °C  
Junction Temperature ..... +150 °C Maximum
- Maximum Power Dissipation  
Total Power Dissipation (Ta=25°C) ..... 800 mW
- Maximum Voltages and Currents (Ta=25°C)  
VCBO Collector to Base Voltage ..... -30 V  
VCEO Collector to Emitter Voltage ..... -25 V  
VEBO Emitter to Base Voltage ..... -5 V  
IC Collector Current ..... -1 A

## Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-30	-	-	V	IC=-100uA, IE=0
BVCEO	-25	-	-	V	IC=-10mA, IB=0
BVEBO	-5	-	-	V	IE=-100uA, IC=0
ICBO	-	-	-100	nA	VCB=-30V, IE=0
*VCE(sat)	-	-	-0.5	V	IC=-1A, IB=-100mA
*VBE(sat)	-	-	-1.2	V	IC=-1A, IB=-100mA
*hFE	70	-	400		VCE=-1V, IC=-100mA
fT	-	110	-	MHz	VCE=-6V, IC=-10mA, f=100MHz
Cob	-	18	-	pF	VCB=-6V, f=1MHz

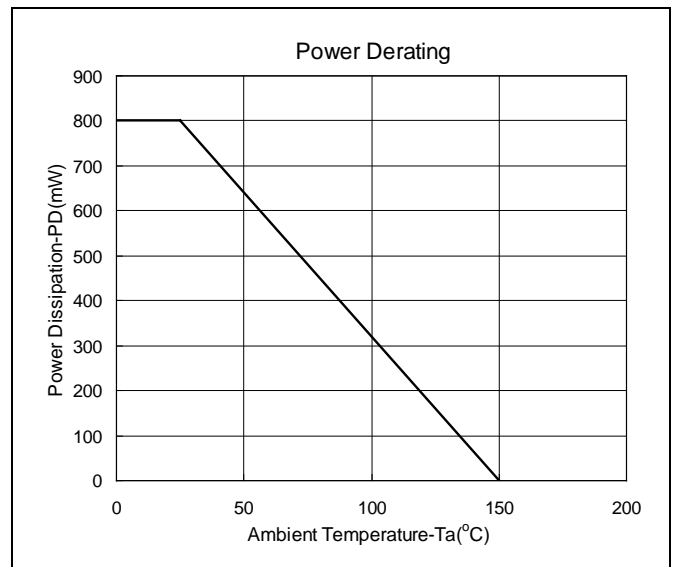
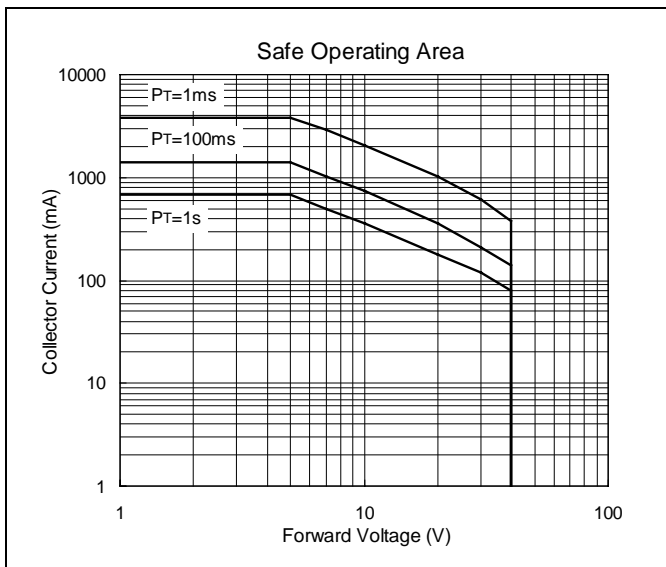
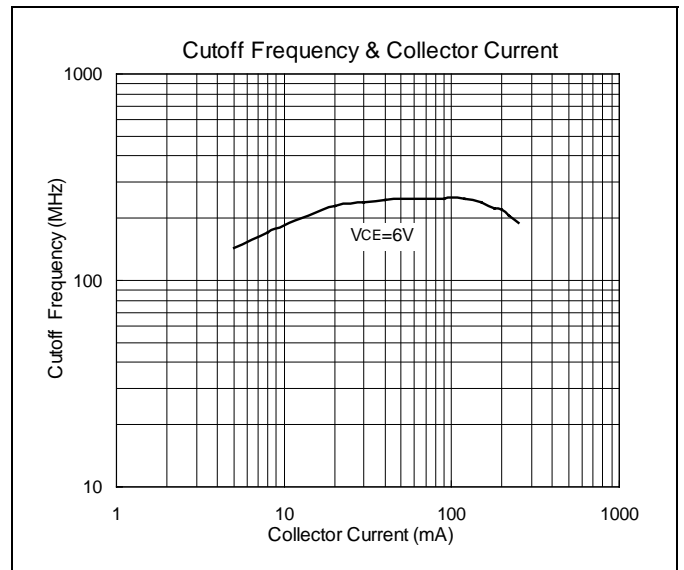
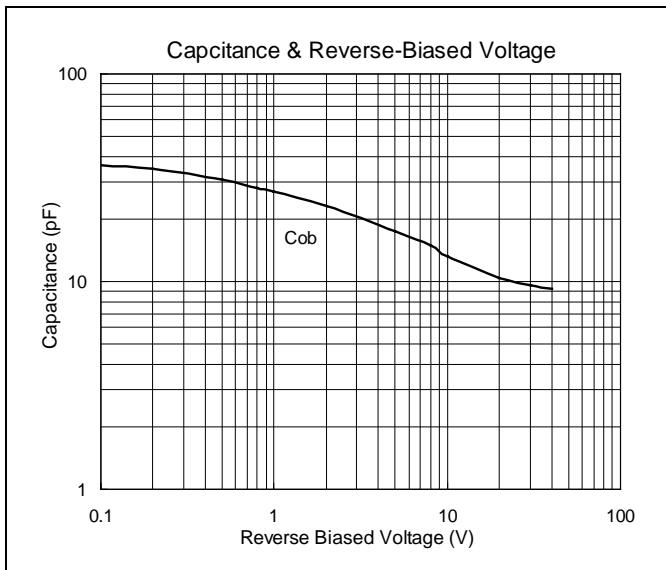
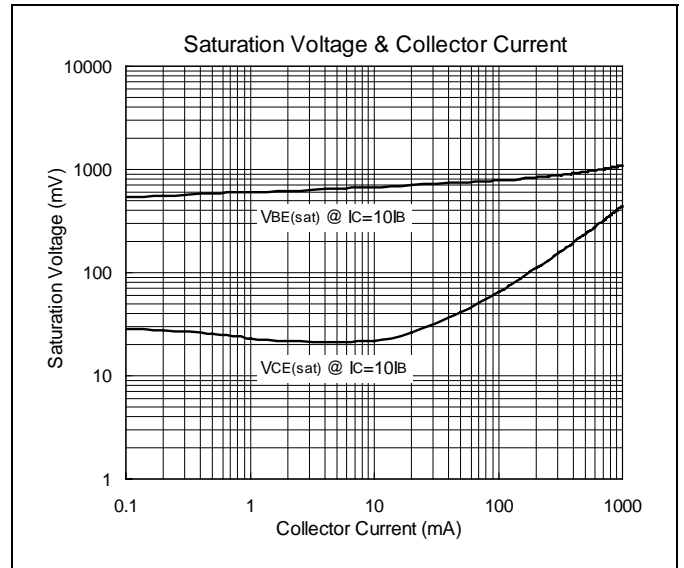
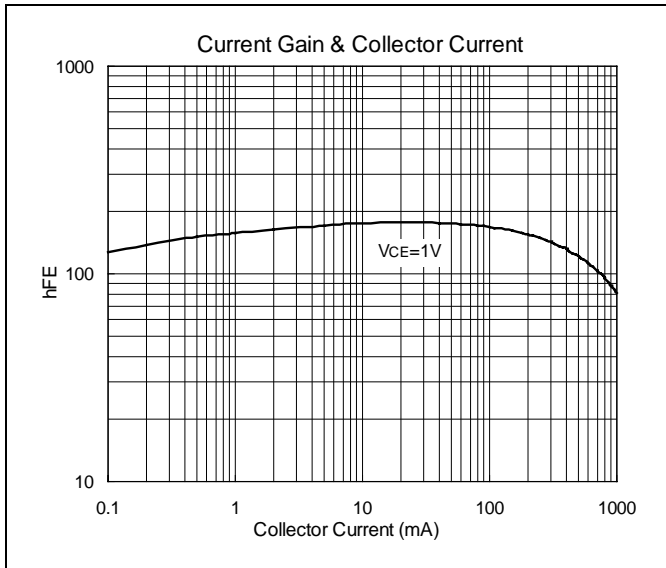
\*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

## Classification Of hFE

Rank	O	Y	GR
Range	70-140	120-240	200-400

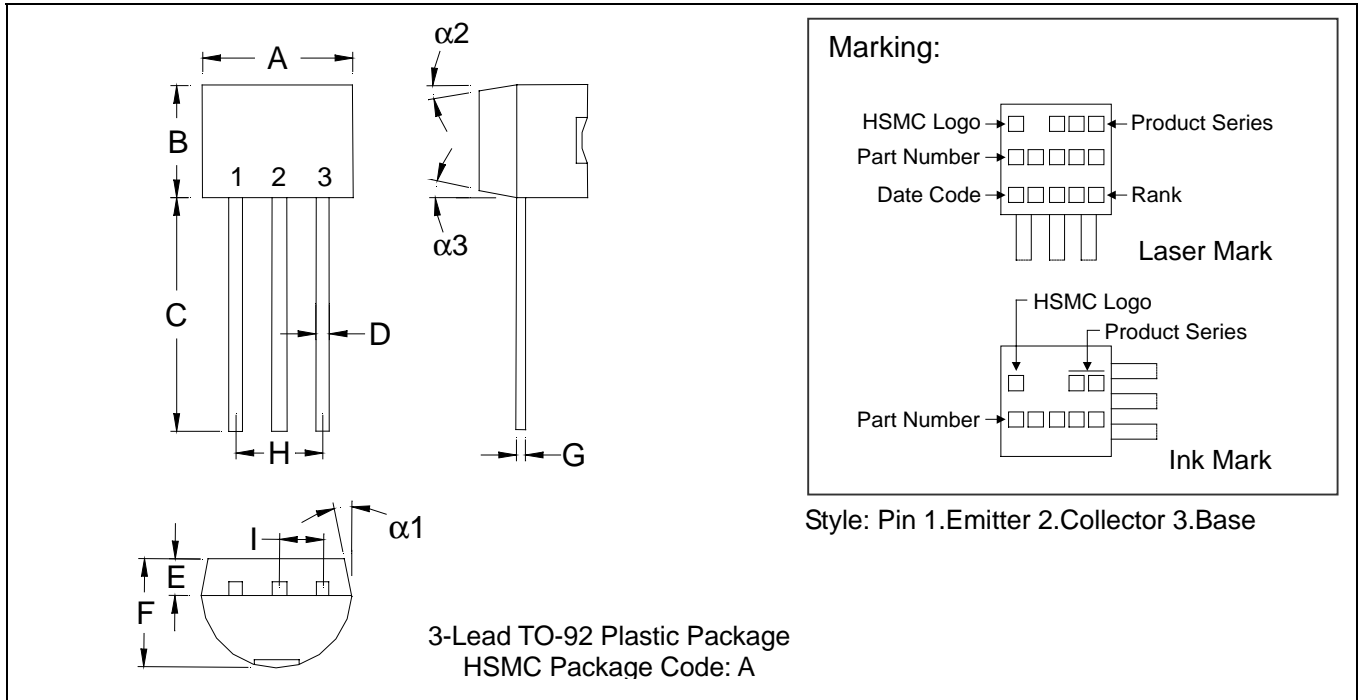


### Characteristics Curve





## TO-92 Dimension



\*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	$\alpha 1$	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	$\alpha 2$	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	$\alpha 3$	-	*2°	-	*2°

- Notes:**
1. Dimension and tolerance based on our Spec. dated Apr. 25, 1996.
  2. Controlling dimension: millimeters.
  3. Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
  4. If there is any question with packing specification or packing method, please contact your local HSMC sales office.

**Material:**

- Lead: 42 Alloy ; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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